



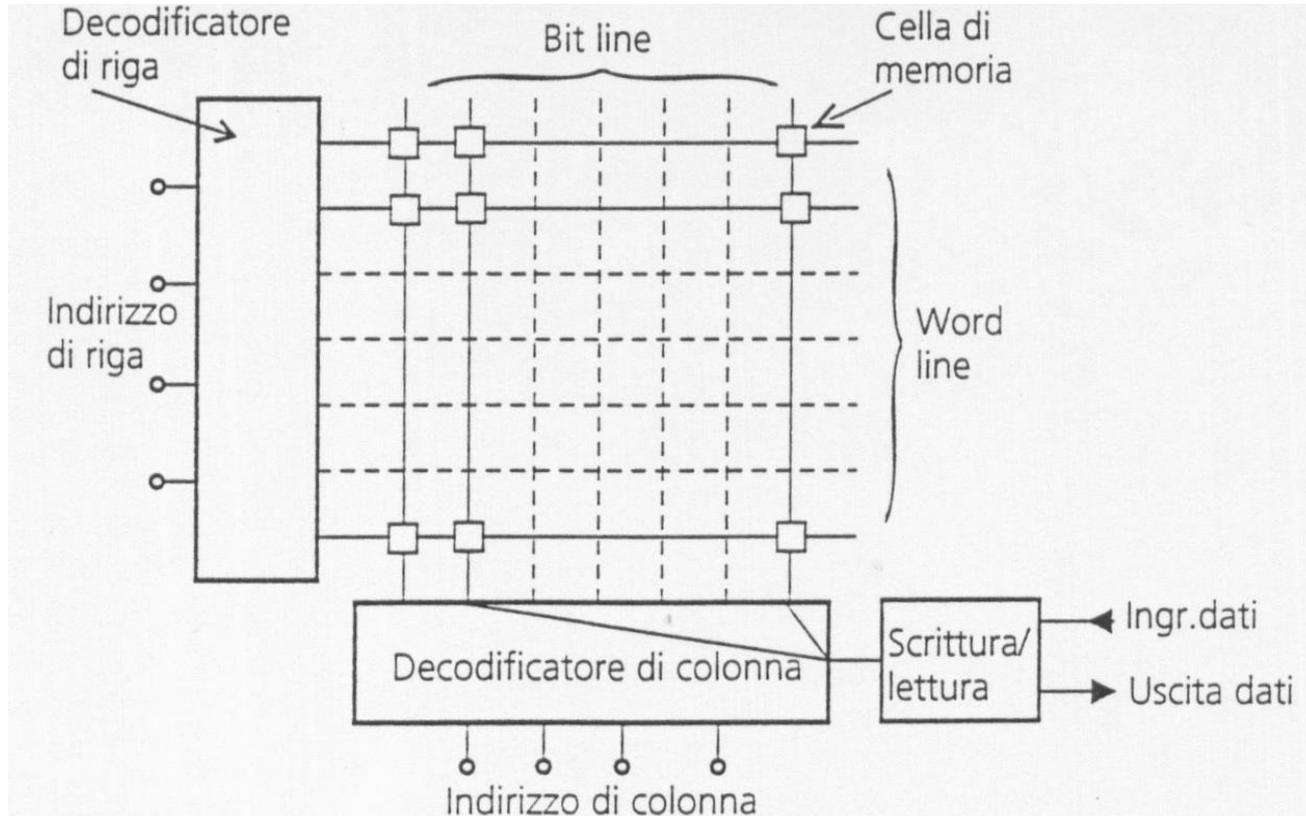
UNIVERSITÀ  
DEGLI STUDI DI TRIESTE



# Le memorie RAM

## A.Carini – Elettronica digitale

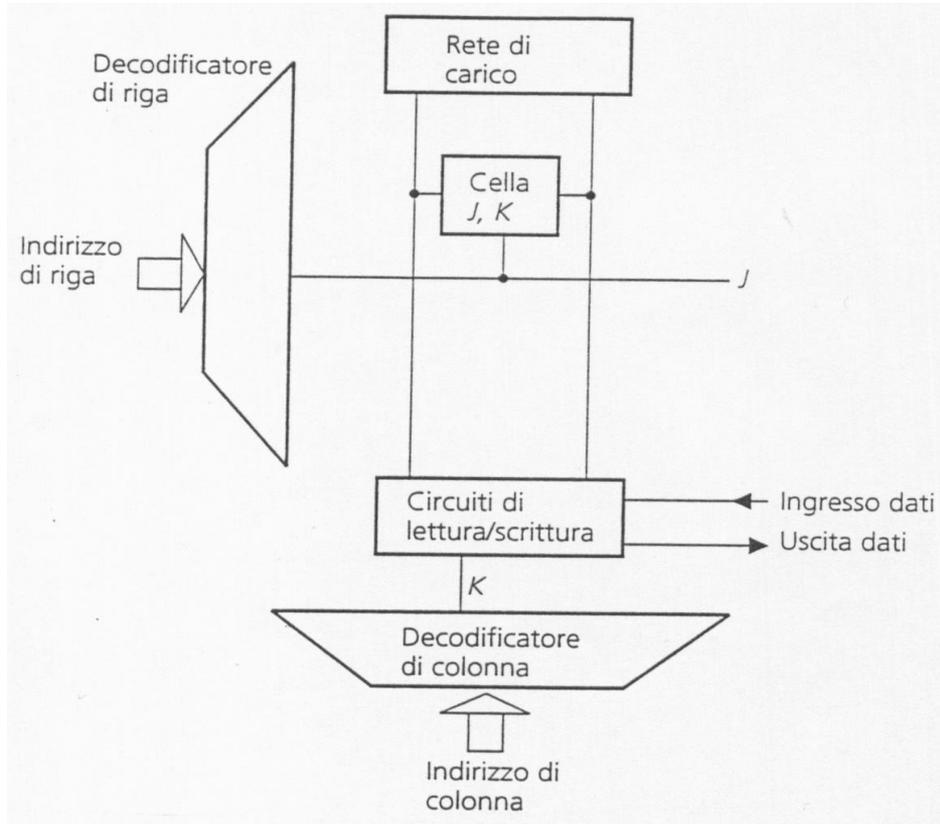
# Schema generale



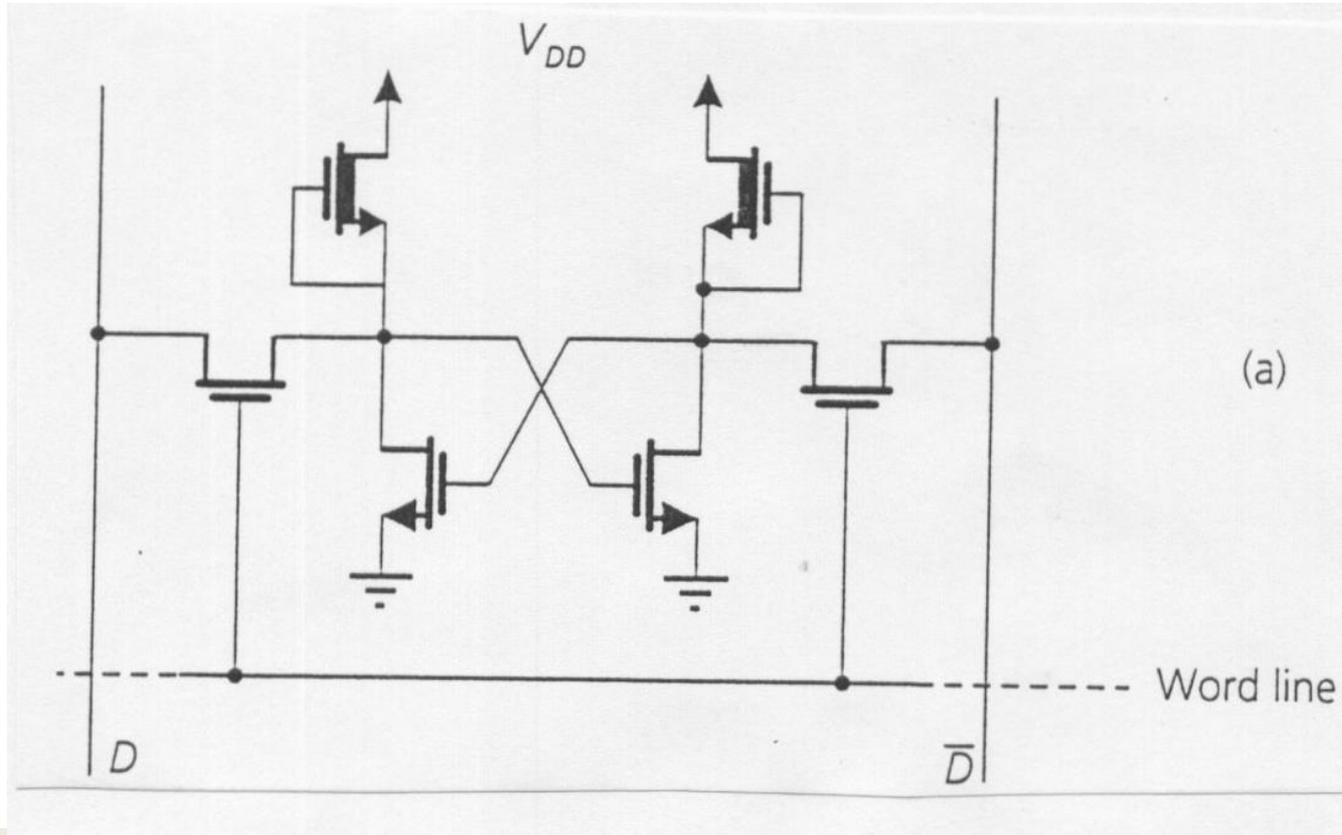
## RAM da 64 Kbit

- Indirizzabile con parole da 16 bit
- 8 bit per le righe, 8 per le colonne
- Decodificatori di riga e di colonna(da 8 a 28) richiedono  $8 \times 256 = 2048$  dispositivi
- Amplificatori di lettura / scrittura sono 256
- Celle di memoria sono 65536 !!!

# Connessione delle celle elementari



# Celle in tecnologia MOS



## Celle in tecnologia MOS

- Consideriamo memoria da 128 Kbit
- Package dual in line che dissipa 320 mW

$$P_d = \frac{320 \cdot 10^{-3}}{128 \cdot 10^3} \cong 2.5 \cdot 10^{-6} \text{ W / cella}$$

$$V_{DD} = 5 \text{ V}$$

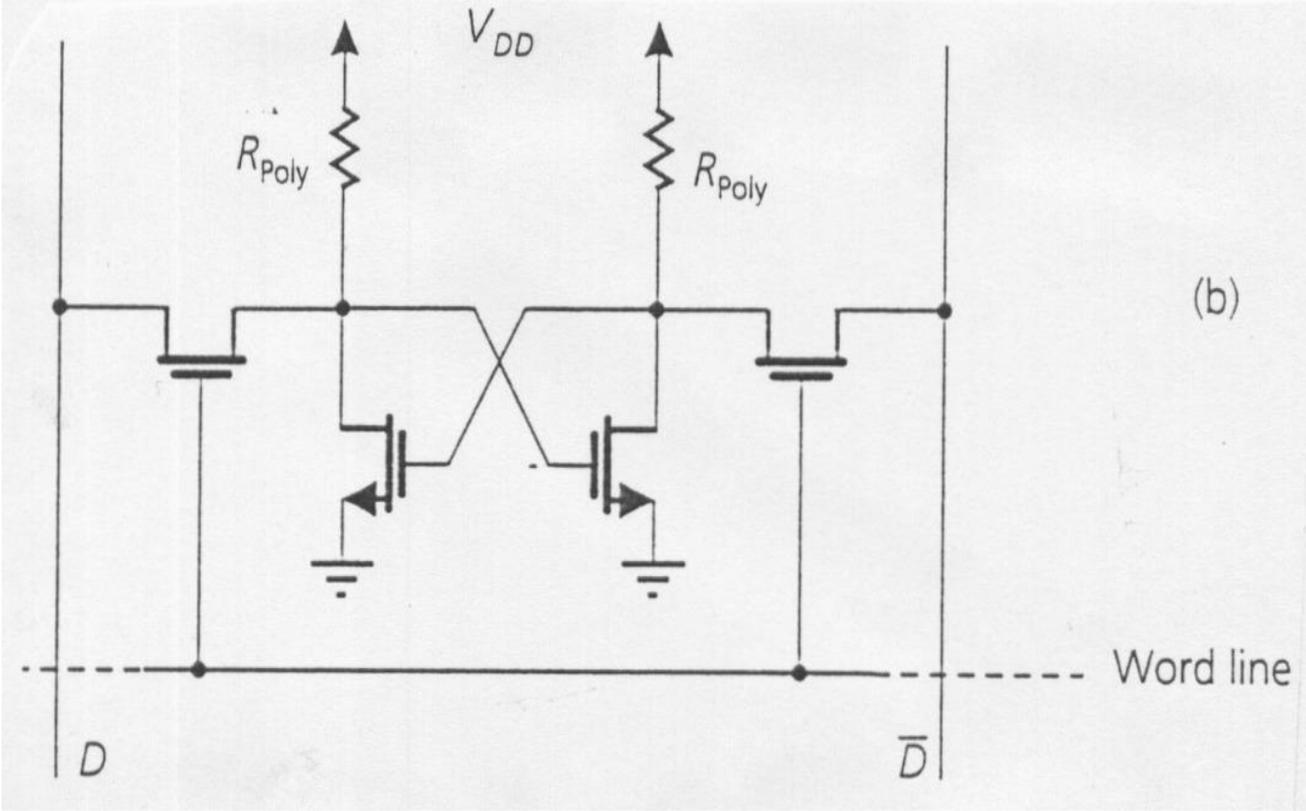
$$P_d = V_{DD} I_L$$

$$I_L = \frac{2.5}{5} \cdot 10^{-6} \text{ A} = 0.5 \mu\text{A}$$

## Celle in tecnologia MOS

- Con un carico attivo dovremmo avere  $W/L < 10^{-2}$  quindi delle lunghezze di canale inaccettabili.
- Il carico per questo motivo viene realizzato in polisilicio non drogato, che può assumere valori di resistenza di strato di  $10^6 \div 10^8 \Omega/\text{quadro}$
- Per realizzare una resistenza di  $10 \text{ M}\Omega$  con una resistenza di strato di  $5 \text{ M}\Omega/\text{quadro}$  bastano due soli quadri.

# Celle SRAM in tecnologia MOS

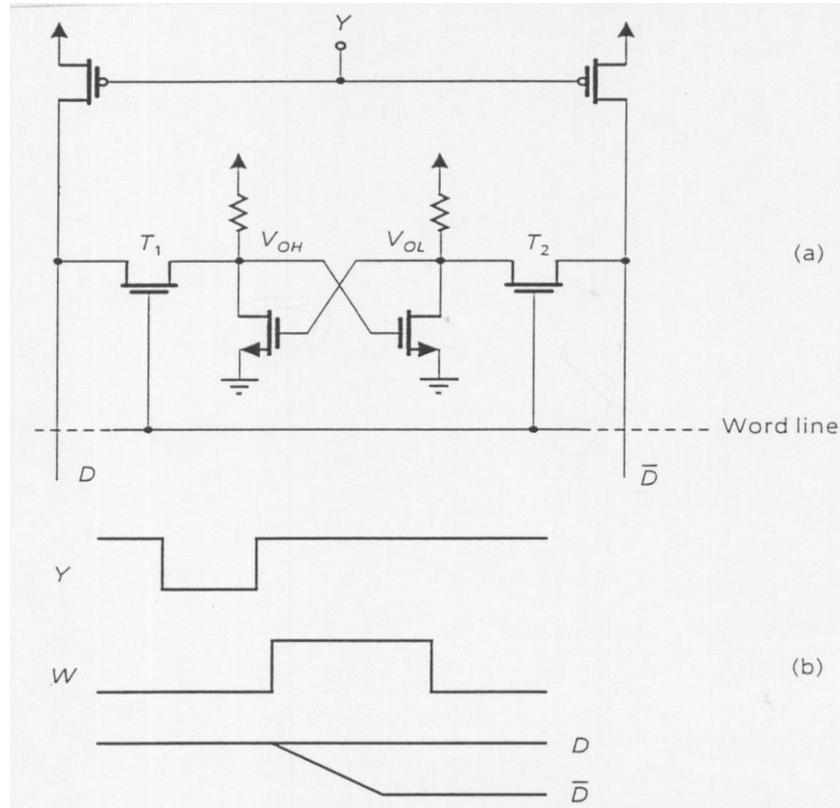




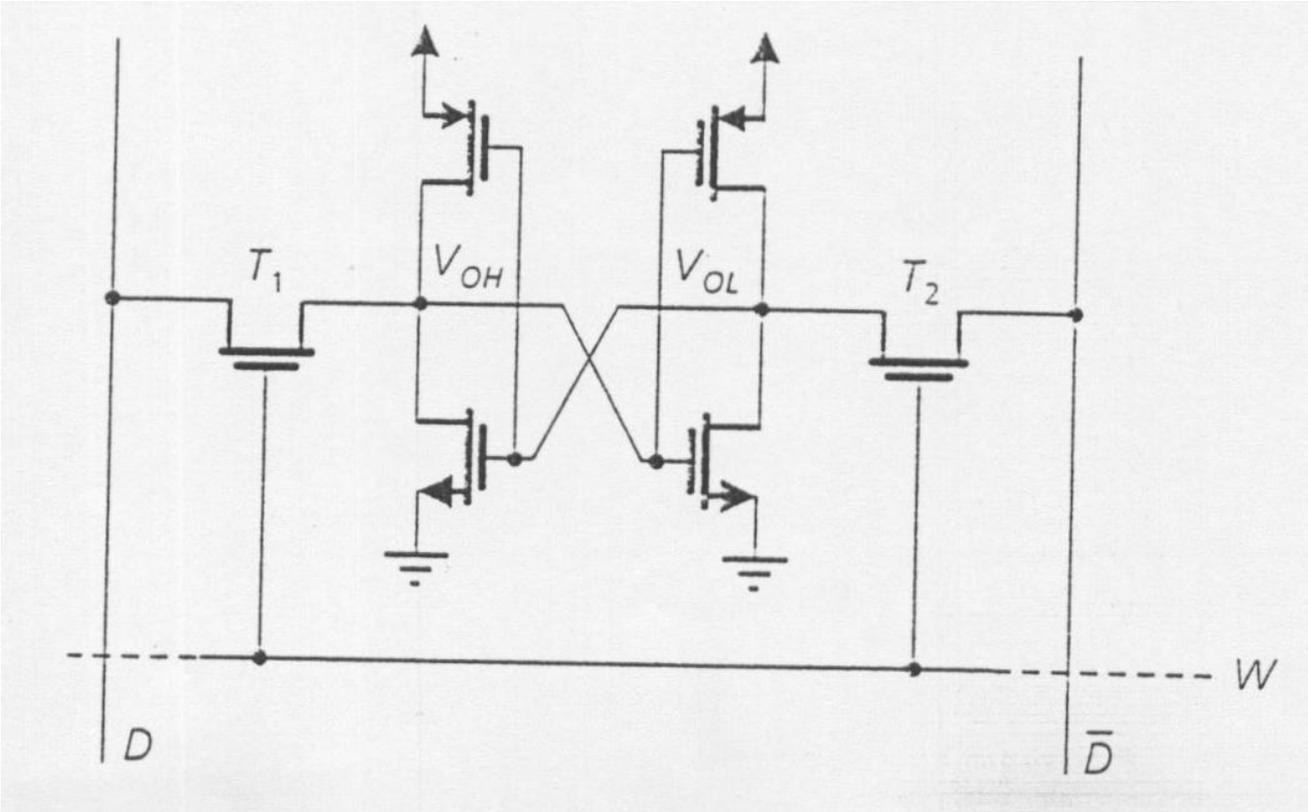
## Ipotesi precarica della linea a 0 V

- $R_{\text{poly}} = 10 \text{ M}\Omega$
- Chip abbia 1 cm di lato
- Bitline  $8 \text{ mm} \times 4 \text{ }\mu\text{m}$
- Area della bitline  $3.2 \cdot 10^4 \text{ }\mu\text{ m}^2$
- $t_{\text{OX}} = 1 \text{ }\mu\text{m}$
- $C_{\text{metal}} = 3 \cdot 10^{-5} \text{ pF} / \text{ }\mu\text{ m}^2$
- $C_{\text{TOT}} = 3 \cdot 10^{-5} \cdot 3.2 \cdot 10^4 \approx 1 \text{ pF}$
- $T = R_{\text{poly}} C_{\text{TOT}} = 10 \text{ }\mu\text{s}$  che è inaccettabilmente lungo

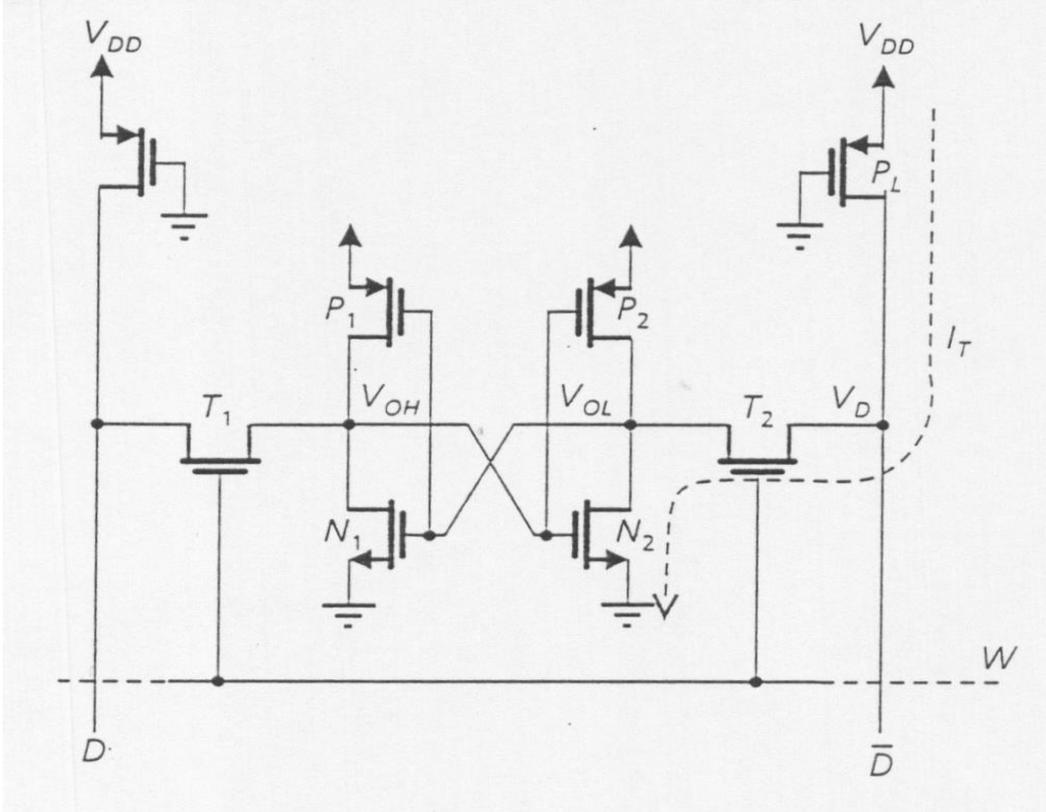
# Rete di precarica



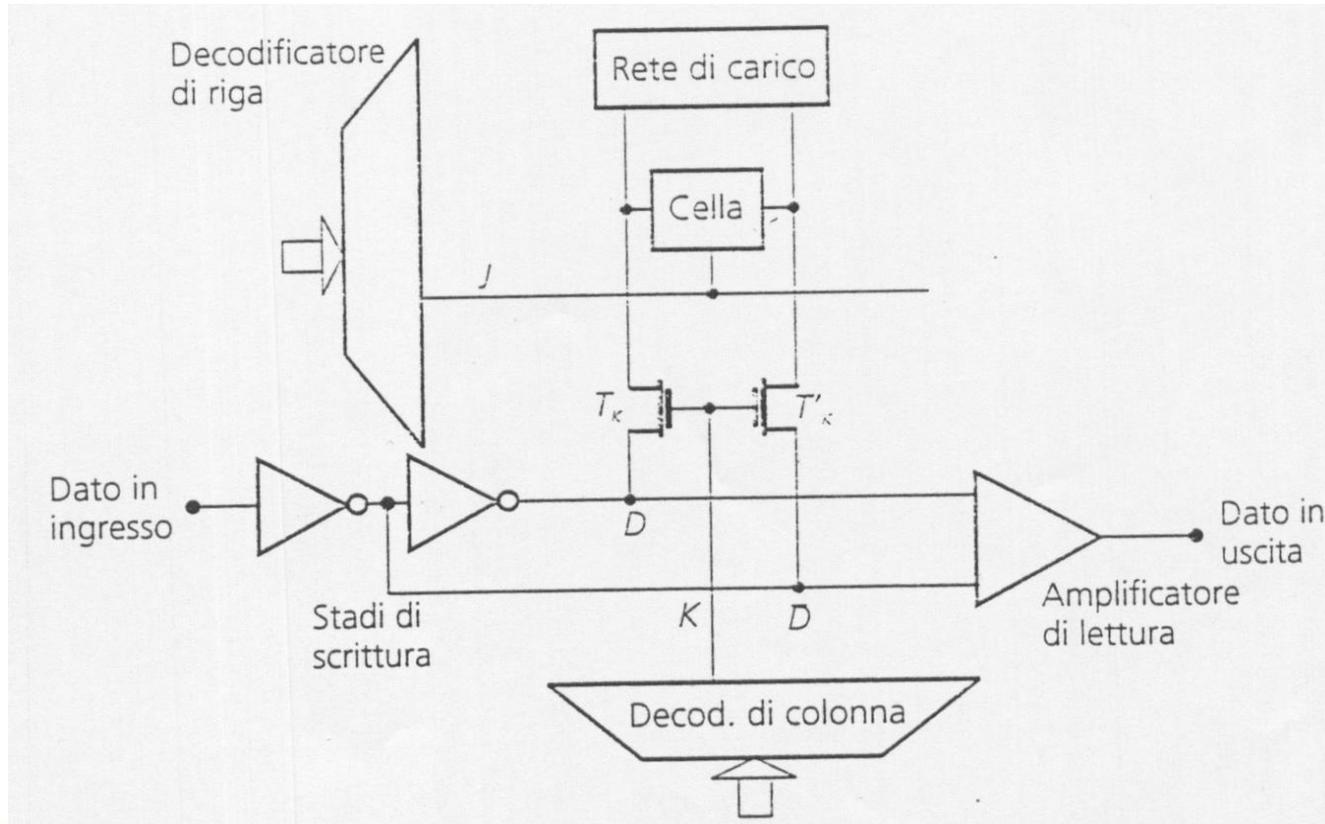
# Cella SRAM CMOS



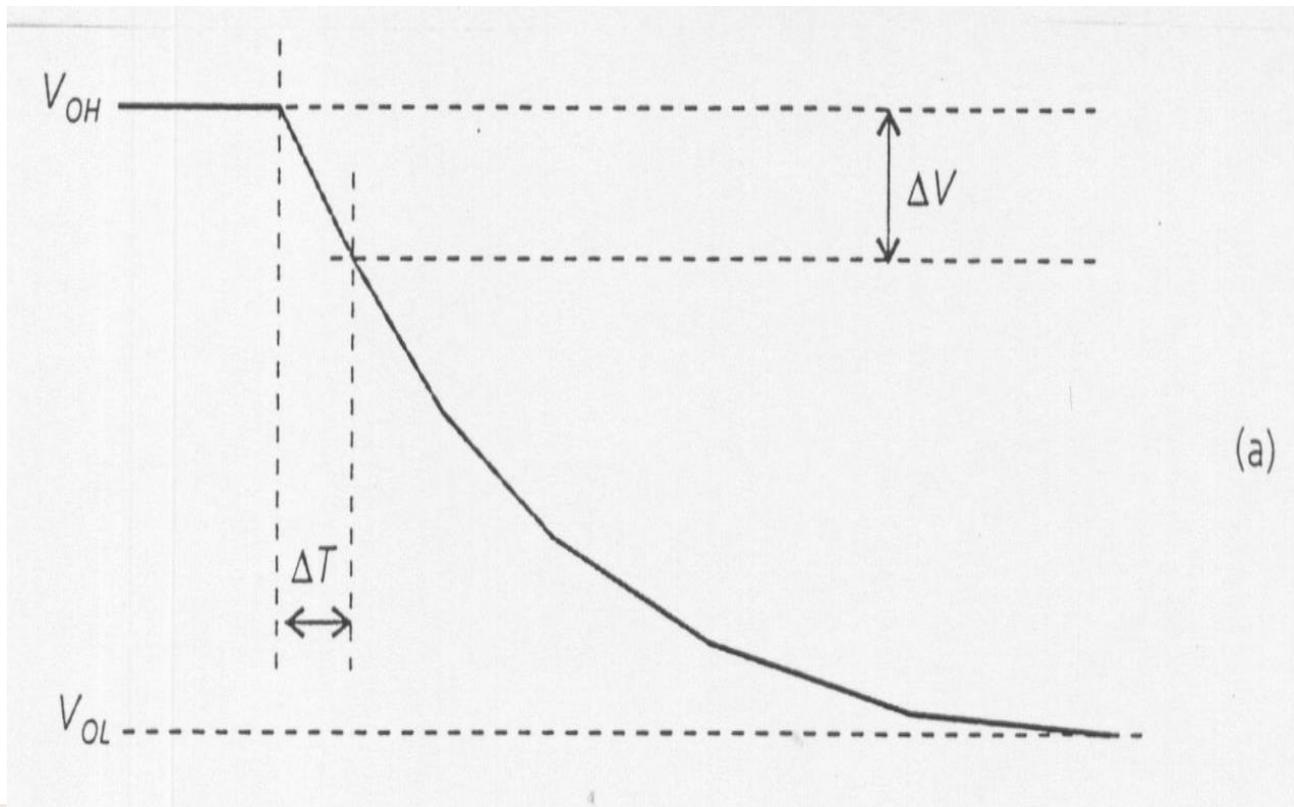
# Cella SRAM CMOS



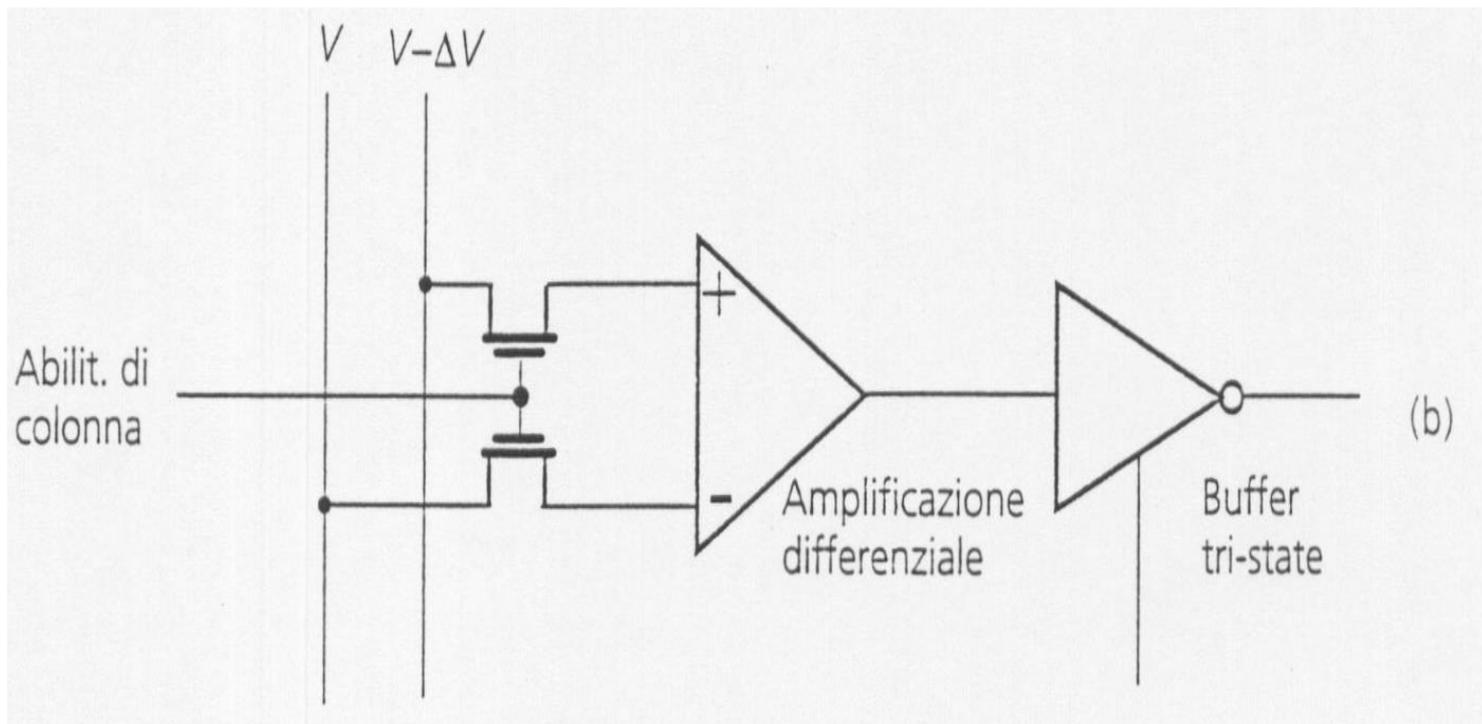
# Circuiti di lettura e scrittura



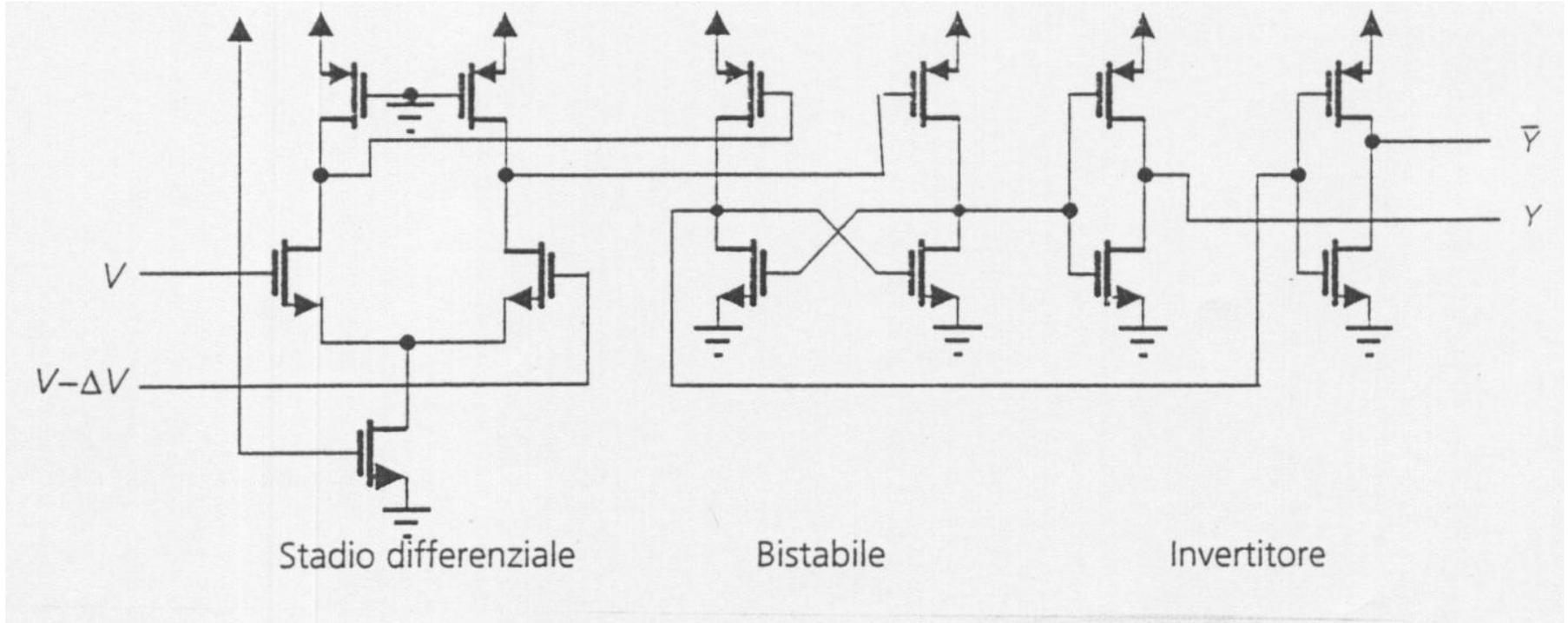
# Amplificatore di lettura



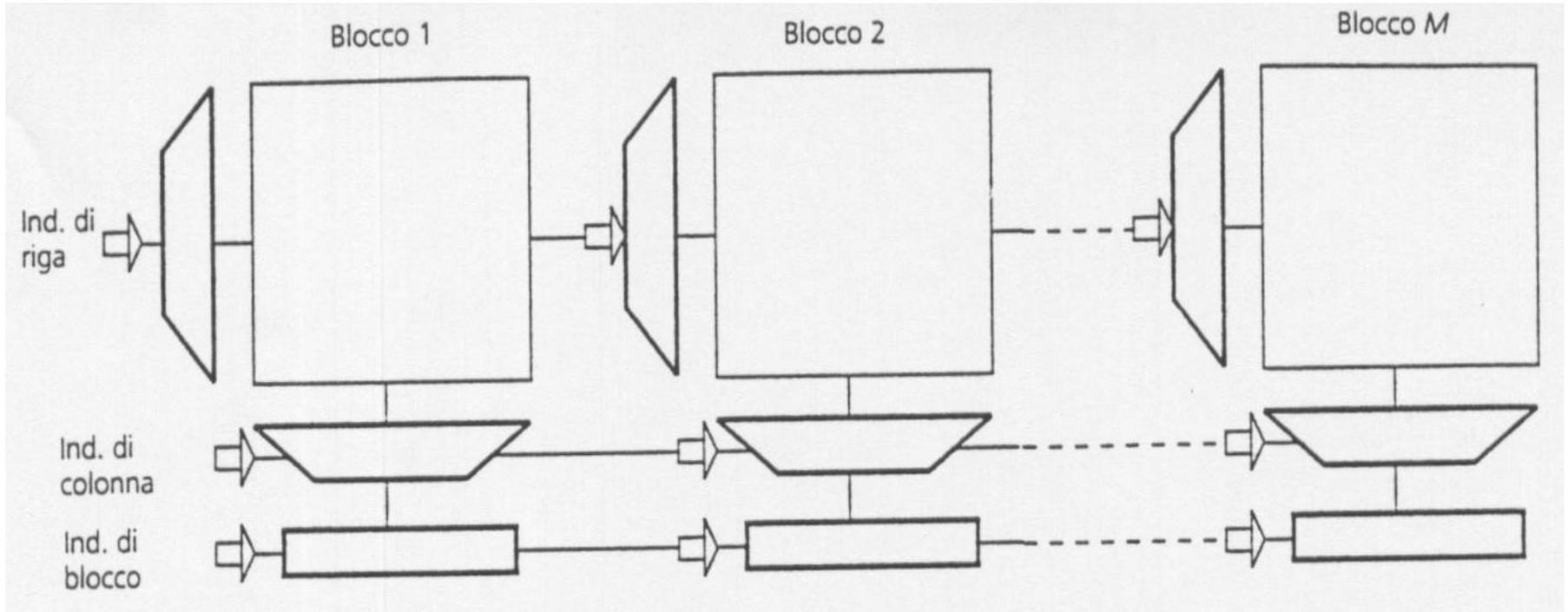
# Amplificatore di lettura



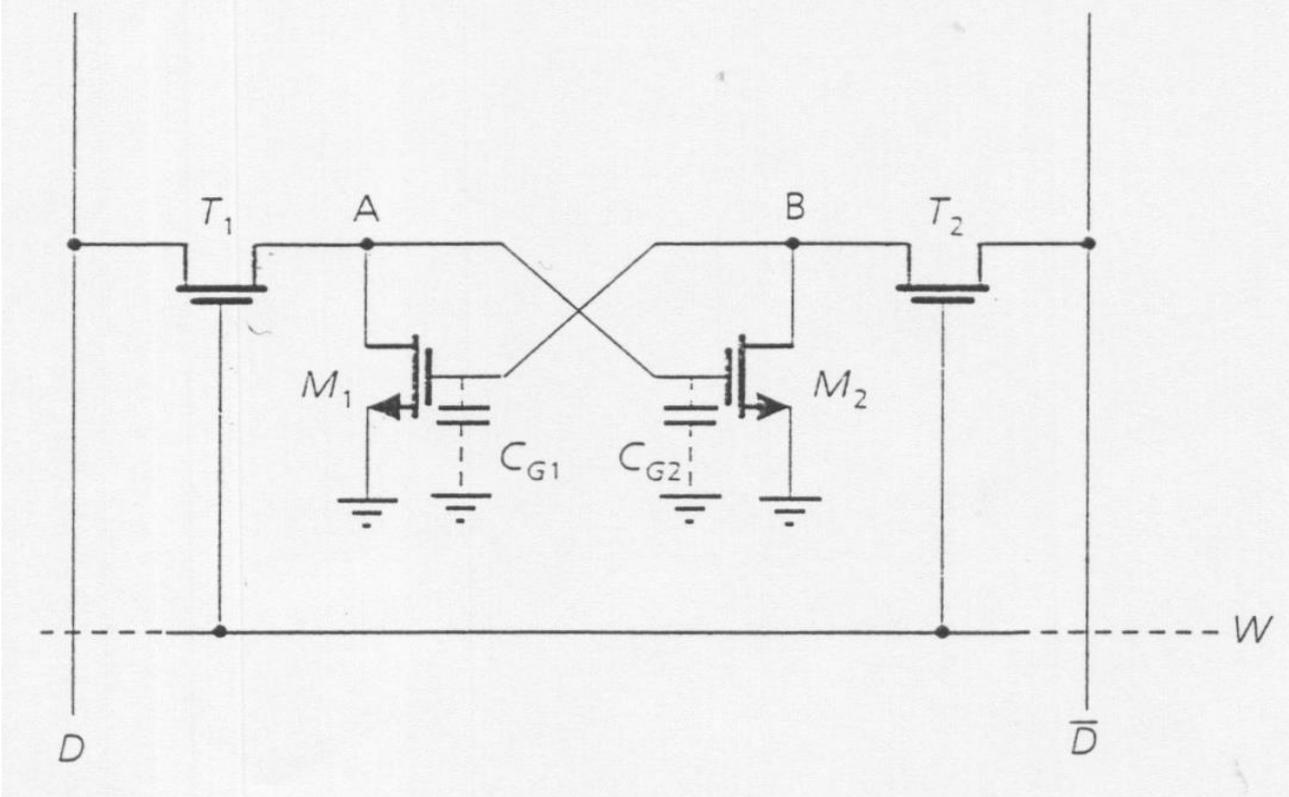
# Amplificatore di lettura



# Organizzazione delle RAM

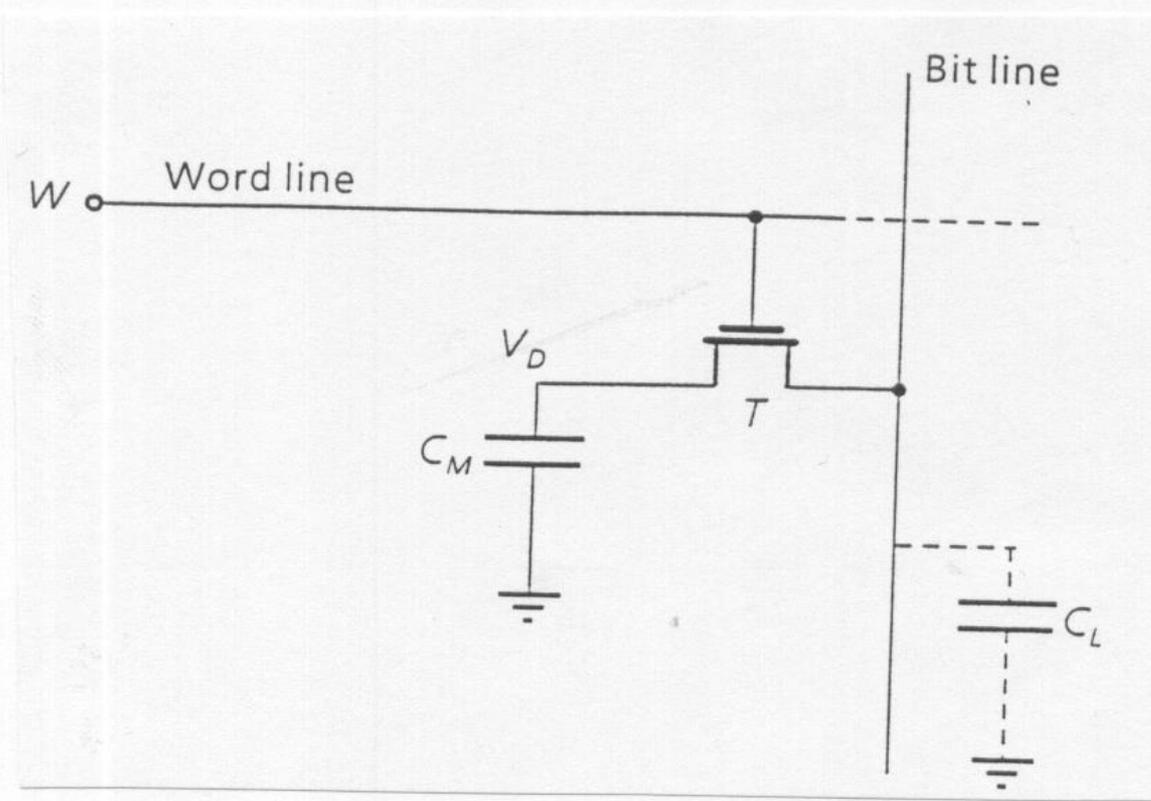


# Cella DRAM a 4 transistori





# Cella dinamica ad 1 transistor



## Ridistribuzione della carica in lettura

$$Q = C_L V_R + C_M V_D = V_R' (C_L + C_M)$$

$$V_R' = \frac{C_L}{C_L + C_M} V_R + \frac{C_M}{C_L + C_M} V_D$$

$$\Delta V_R = V_R - V_R' = \frac{C_M}{C_L + C_M} (V_R - V_D)$$

Es:

$$C_M \ll C_L$$

$$C_M = 25 \text{ fF}$$

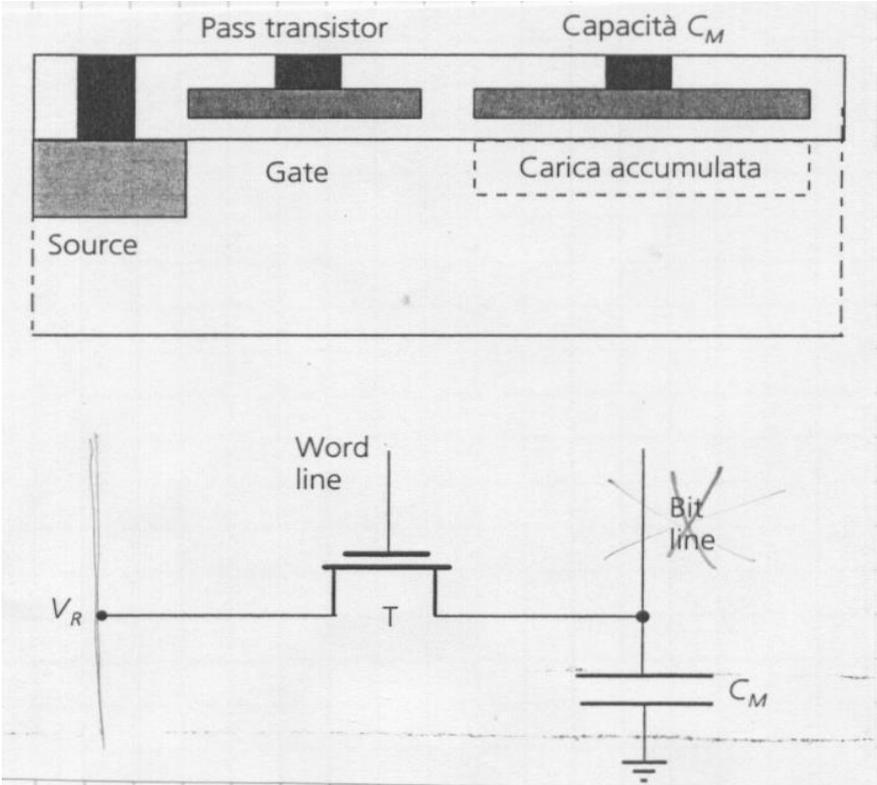
$$C_D = 1 \text{ pF}$$

$$V_R = 5 \text{ V}$$

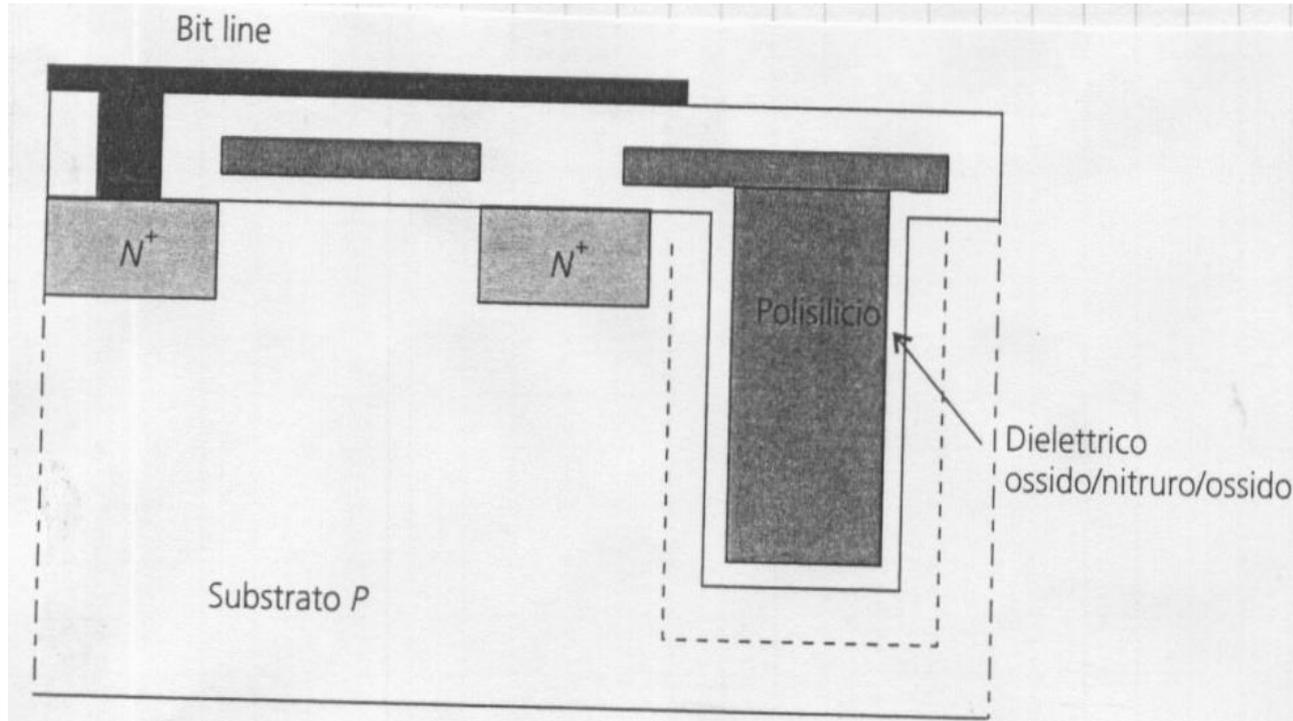


$$\Delta V_R = 125 \text{ mV}$$

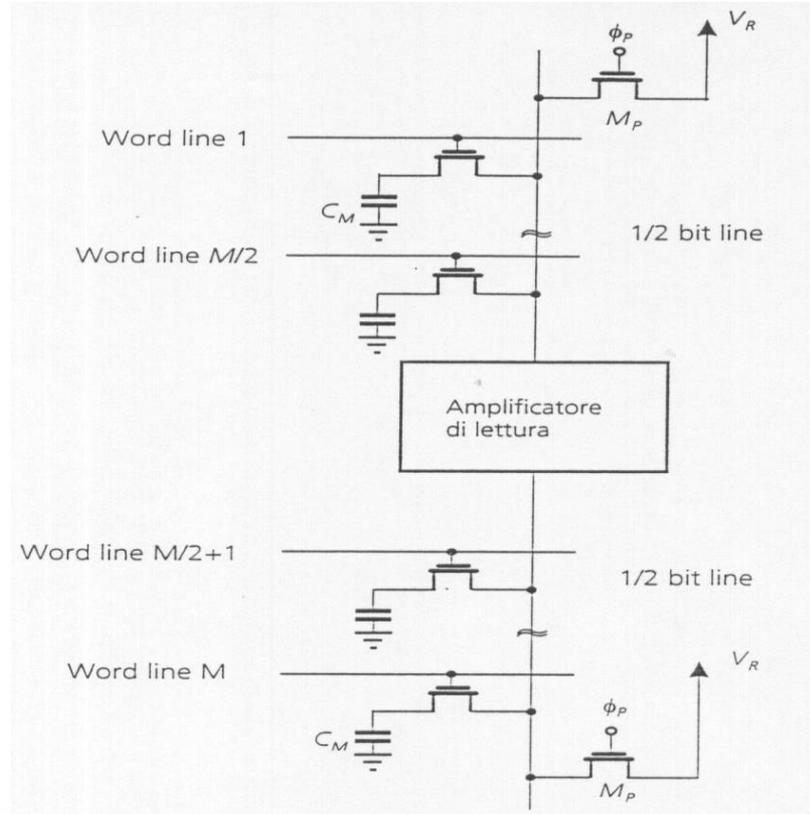
# Cella di memoria



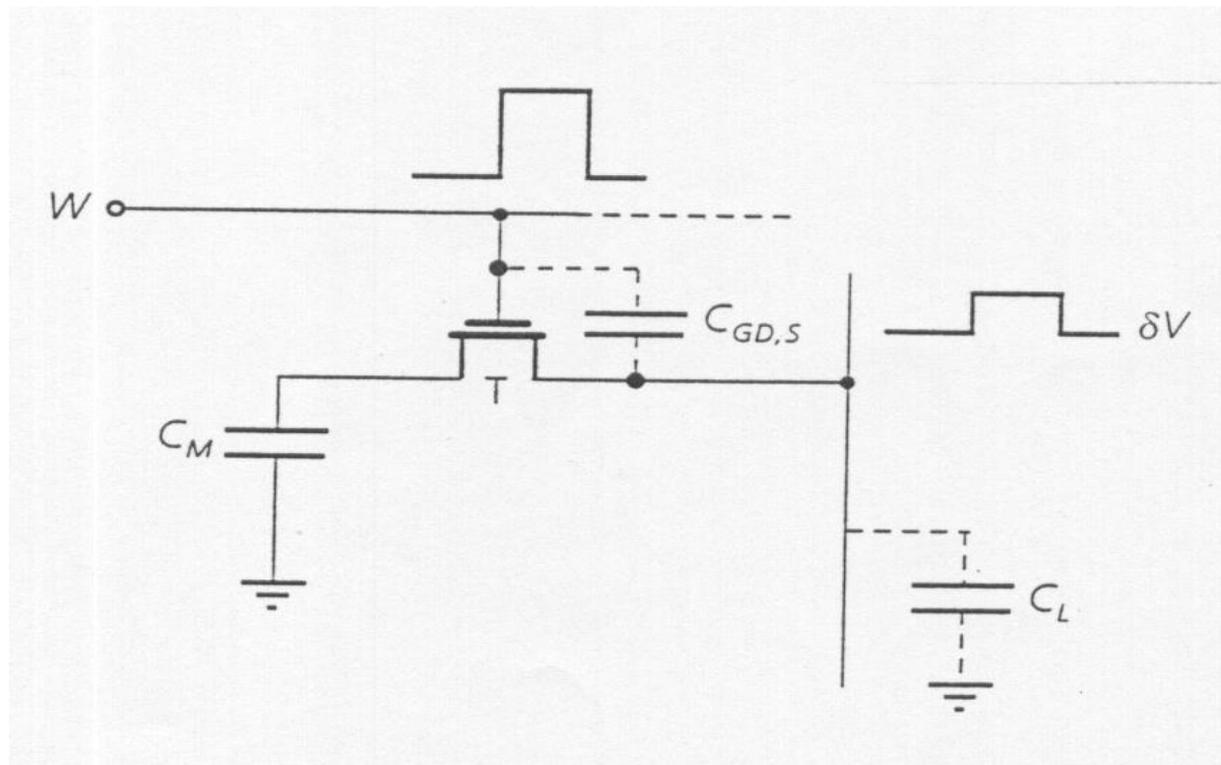
# Trench capacitor



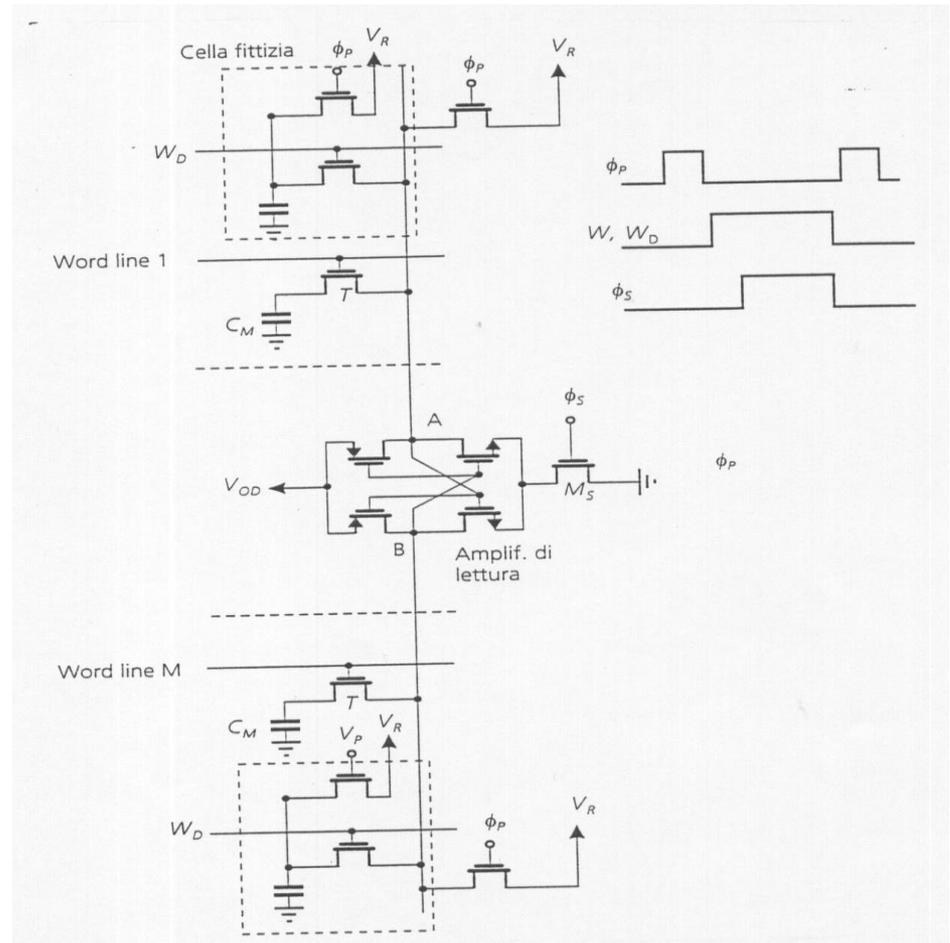
# Circuiti di lettura per DRAM



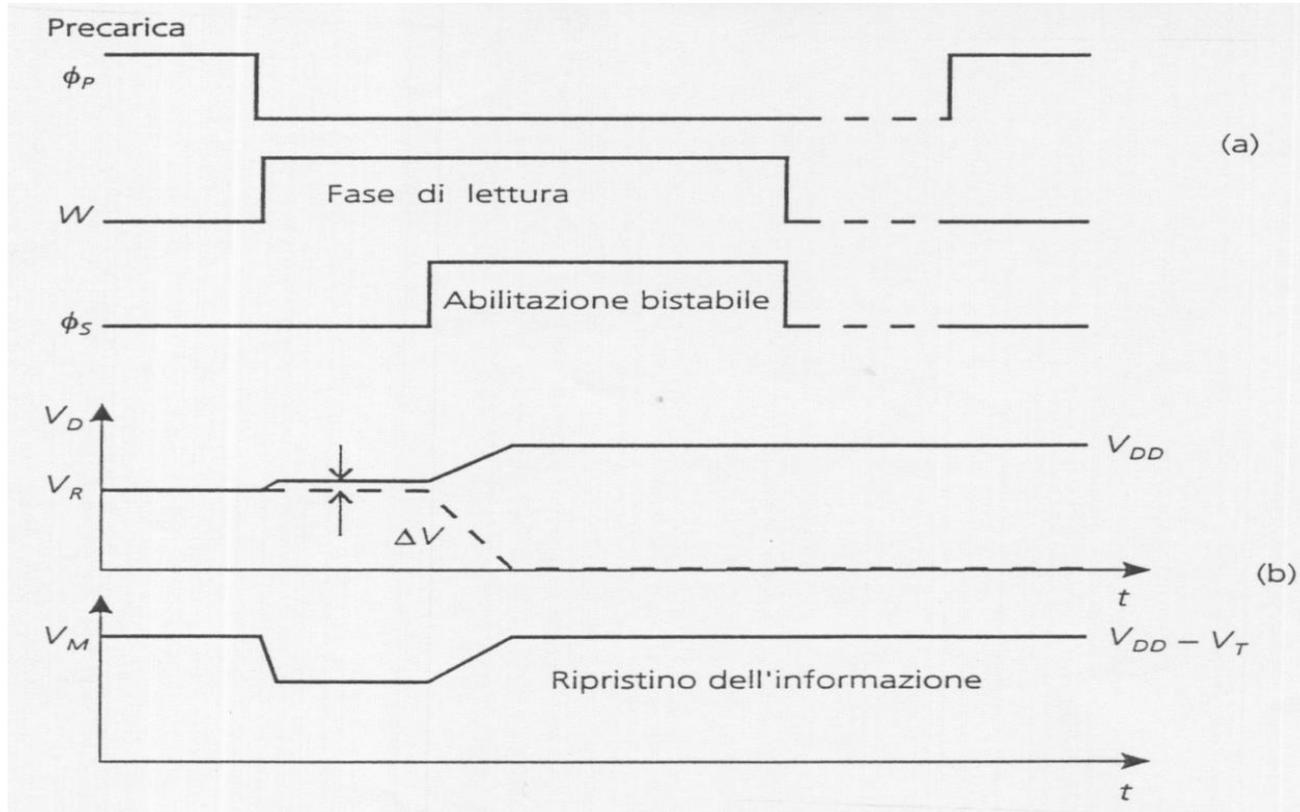
# Circuiti di lettura per DRAM



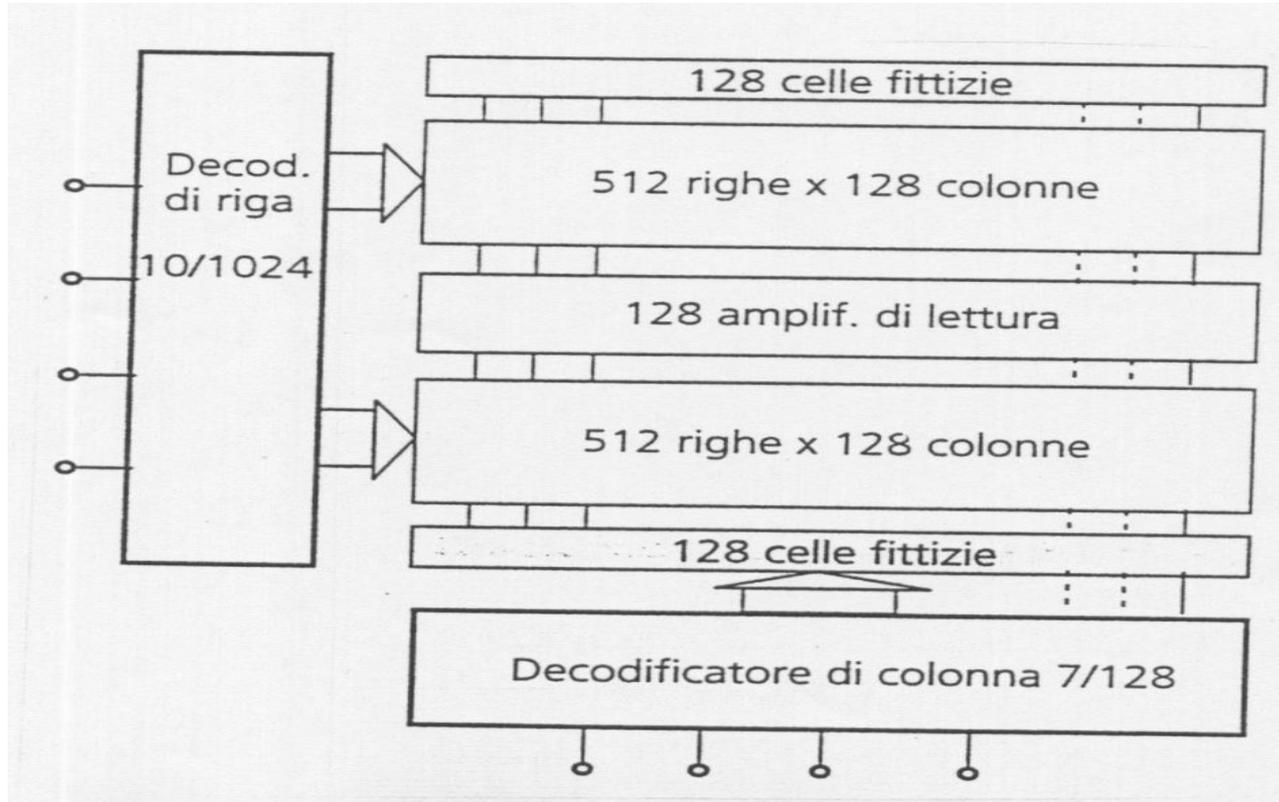
# Circuiti di lettura per DRAM



# Circuiti di lettura per DRAM



# Organizzazione della DRAM



## Vedere:

- Paolo Spirito, “Elettronica Digitale”, Ed. McGraw-Hill
  - Cap. 13.4-13.8